

## B4BQDD4DRXMC-XX0

### 400GBASE-DR4 QSFP-DD 500m Single Mode Fiber Transceiver

#### Description

APAC's B4BQDD4DRXMC-XX0, 400GBASE-DR4, hot pluggable optical transceiver is a high-performance solution for 400 Gigabit Ethernet links for up to 500m over single mode fiber (SMF). It combines 8x 26 GBd PAM4 electrical lanes into four 53.125 GBd PAM4 optical channels in compliance with IEEE 400GBASE-DR4. Superior performance and reliability is achieved through APAC's advanced transmitter and receiver design using cooled 4x EA-DFB-LDs and 4x PIN PDs with low-power TIAs.



#### Features

- 400GBASE-DR4 compliant
  - 4x 53.125GBd PAM4
- 400GAUI-8 compliant
  - 8x 26.5625 Gb/s PAM4
- QSFP-DD MSA compliant
- MPO-12 connector
- Power consumption <12W
- Operating case temperature 0 to 70°C
- CMIS 4.0 management interface
- Two-wire management (SFF-8636)

#### Applications

- Data Center 400 Gigabit Ethernet 500m SMF links
- 4:1 breakout with 100GBASE-DR
- Upgrading 100G PSM4 to 400G
- Switch/Router interconnections



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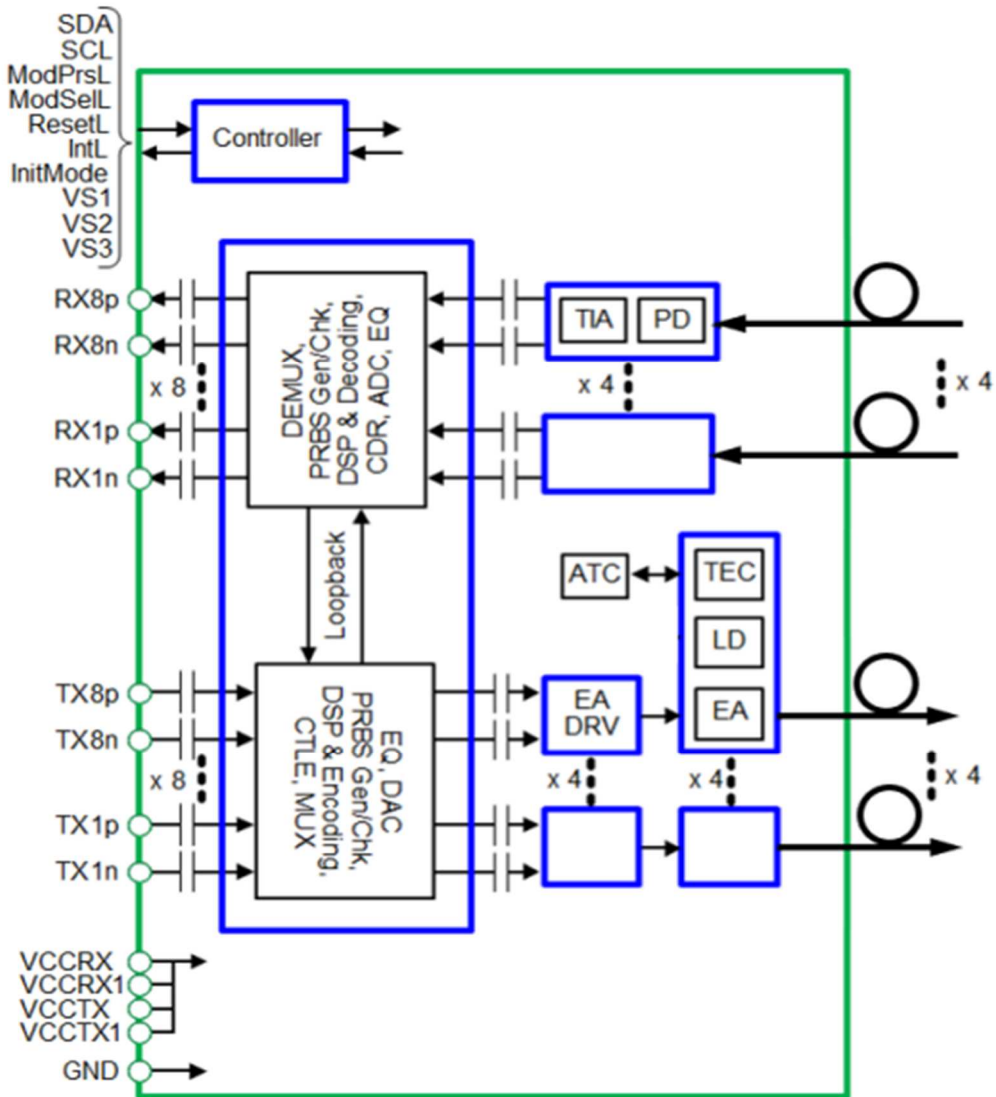
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## 1 FUNCTIONAL DESCRIPTION

APAC's B4BQDD4DRXMC-XX0 is a fully integrated, 425 Gb/s optical channel transceiver for SMF links up to 500m. Its MPO-12 optical connector matches the 100G PSM4 MPO-12 allows existing 100G PSM4 links to be upgraded to 400G without changing the fiber infrastructure. The B4BQDD4DRXMC-XX0 has four parallel 1.3  $\mu\text{m}$  optical channels with 4-level pulse amplitude modulation (PAM4) format and connects to a PAM4-based 8 channel x 26.5625 Gb/s 400GAUI-8 electrical interface. By means of a 2:1 mux/demux and APAC's cooled EA-DFB-LD advanced transmitter design and its low-power PIN-PD + TIA receiver, superior performance and reliability is achieved.

QSFP-DD assures mechanical and electrical compatibility with QSFP28 and QSFP+. Hence, the same port can be used to support multiple generations of modules and data rates if the networking hardware is designed for such operation.

The SFF-8636 and CMIS 4.0 compliant 2-wire management interface enables control, alarm and monitoring of the B4BQDD4DRXMC-XX0.



**Figure 1 Functional Block Diagram**



## 2 PERFORMANCE SPECIFICATIONS

### 2.1 Absolute Maximum Ratings

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. These are absolute stress ratings only. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of the data sheet. Exposure to absolute maximum ratings will cause permanent damage and/or adversely affect device reliability.

**Table 1 Absolute Maximum Ratings**

No.	Parameter	Symbol	Min.	Max.	Unit	Remarks
1	Supply Voltage	Vcc	0	+3.6	V	+3.3 V
2	Storage Temperature		-40	85	°C	
3	Optical Receiver Input		-	+5.0	dBm	Average

### 2.2 Operating Environments

Electrical and optical characteristics below are defined under this operating environment, unless otherwise specified.

**Table 2 Operating Environment**

No	Parameter	Symbol	Min.	Typ.	Max.	Unit	Remarks
1	Supply Voltage	Vcc	3.135	3.3	3.465	V	
2	Supply Voltage Noise Tolerance	PSNR	-	-	66	mV	10 Hz –10 MHz
3	Power Consumption		-	-	12	W	
4	Instantaneous peak current	lcc_ip_6			4800	mA	
5	Sustained peak current	lcc-sp_6			3960	mA	
6	Supply Current	lcc-6	--	-	3827.8	mA	Steady state
7	Case Temperature	TC	0	25	70	°C	



## 2.3 Electrical Interface

**Table 3 Electrical Characteristics**

No.	Parameter	Min.	Typ.	Max.	Unit	Remarks
<b>Module output (each lane, at TP4) [Note 1]</b>						
1	Signaling rate per lane (range)	-100ppm	26.5625	+100ppm	GBd	
2	AC Common-mode output voltage (RMS)	-	-	17.5	mV	
3	Differential peak-to-peak output voltage	-	-	900	mV	
4	Near-end ESMW (Eye symmetry mask width)	0.265	-	-	UI	
5	Near-end Eye height, differential	70	-	-	mV	
6	Far-end ESMW (Eye symmetry mask width)	0.2	-	-	UI	
7	Far-end Eye height, differential	30	-	-	mV	
8	Far-end pre-cursor ISI ratio	-4.5	-	2.5	%	
9	Differential output return loss	Equation (83E-2)	-	-	dB	Note 2
10	Common to differential mode conversion return loss	Equation (83E-3)	-	-	dB	Note 2
11	Differential termination mismatch	-	-	10	%	
12	Transition time (20% to 80%)	9.5	-	-	ps	
13	DC common mode voltage	-350	-	2850	mV	
<b>Module input (each lane)</b>						
1	Signaling rate per lane (range)	-100ppm	26.5625	+100ppm	GBd	
2	Differential pk-pk input voltage tolerance	900	-	-	mV	at TP1a
3	Differential input return loss	Equation (83E-5)	-	-	dB	at TP1, Note 2
4	Differential to common mode input return loss	Equation (83E-6)	-	-	dB	at TP1, Note 2
5	Differential termination mismatch	-	-	10	%	at TP1
6	ESMW (Eye symmetry mask width)	0.22	-	-	UI	at TP1a
7	Eye width	0.22	-	-	UI	at TP1a
8	Applied pk-pk sinusoidal jitter	Table 120E-6			MHz, UI	at TP1a
9	Eye height	32	-	-	mV	at TP1a
10	Single-ended input voltage tolerance	-0.4	-	3.3	V	at TP1a

	range					
11	DC common mode voltage	-350	-	2850	mV	at TP1

Note 1: Electrical module output is squelched for loss of optical input signal.

Note2: IEEE 802.3-2018 Section 6

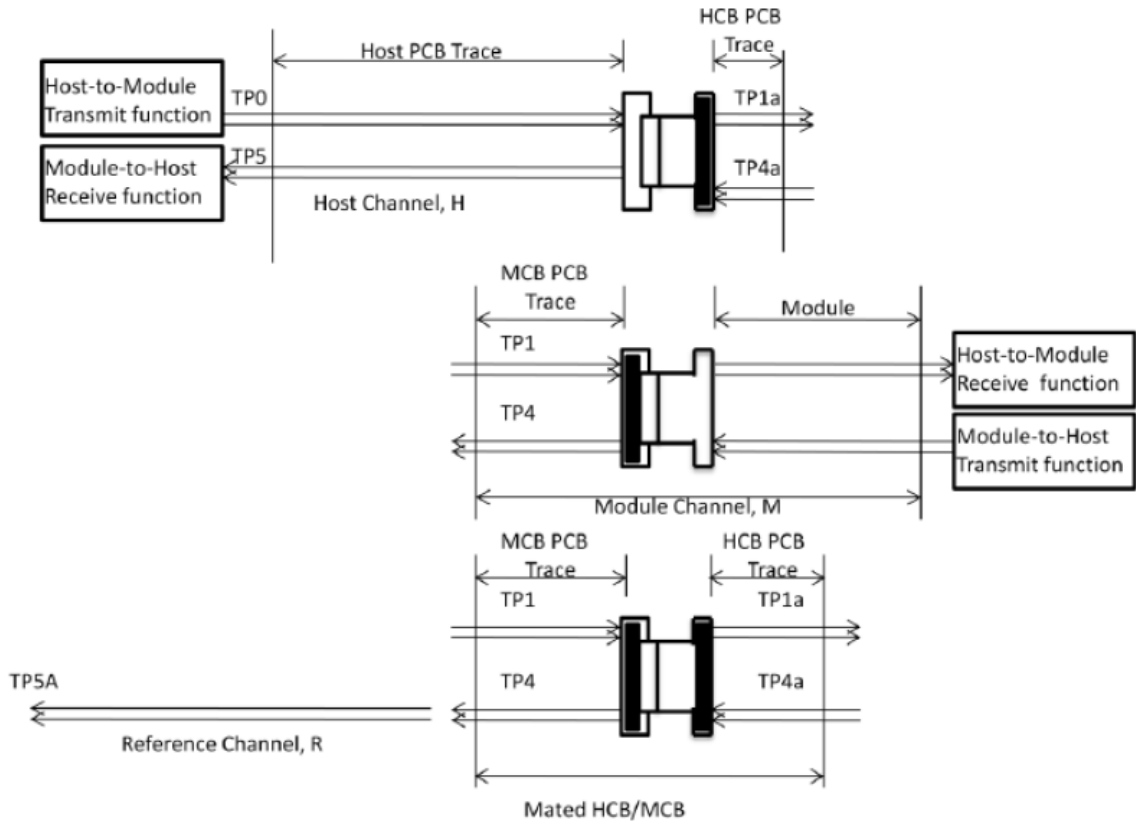


Figure 2 Reference Test Points



## 2.4 Optical Interface

**Table 4 Optical Characteristics**

No.	Parameter	Symbol	Min.	Typ.	Max.	Unit	Remarks
1	Channel data rate	$f_{DC}$	106.25			Gb/s	
2	Signaling rate	$f_{SG}$	53.125			GBd	Per lane
3	Signal speed variation from nominal	$\Delta f_{SG}$	-100		+100	ppm	
4	Lane wavelength (range)	$\lambda_c$	1304.5		1317.5	nm	
5	Side-mode suppression ratio	SMSR	30			dB	
7	Average launch power		-2.9		4.0	dBm	Note 1
8	Outer Optical Modulation Amplitude (OMA <sub>outer</sub> )		-0.8		4.2	dBm	Note 2 Per lane
10	Launch power in OMA <sub>outer</sub> minus TDECQ		-2.2			dBm	Per Lane
11	Transmitter and dispersion eye closure for PAM4	TDECQ			3.4	dB	Per lane
13	Average Optical Output Power of Off Transmitter	$P_{off}$			-15	dBm	Per lane
14	Extinction Ratio	ER	3.5			dB	Per lane
16	RIN <sub>21.4OMA</sub>				-136	dB/H z	
17	Optical return loss tolerance				21.4	dB	
18	Transmitter reflectance				-26	dB	Note 3
19	Average receive power		-5.9		4.0	dBm	Note 4
20	Receive power (OMA <sub>outer</sub> )				4.2	dBm	Per lane
22	Receiver reflectance				-26	dB	
23	Receiver sensitivity (OMA <sub>outer</sub> )		Max (-3.9, SECQ - 5.3), Figure 5				Note 5, 6
24	Stressed receiver sensitivity (OMA <sub>outer</sub> )				-1.9	dBm	Note 5, 7 Per lane
Conditions of stressed receiver sensitivity test [Note 8]							
25	Stressed eye closure for PAM4 (SECQ), lane under test	SECQ	3.4			dB	
27	OMA <sub>outer</sub> of each aggressor lane		4.2			dBm	

Note 1: Average launch power, each lane (min) is informative and not the principal indicator of signal strength. A transmitter with launch power below this value cannot be compliant; however, a value above this does not ensure compliance.

Note 2: Even if the TDECQ < 1.4 dB, the OMA<sub>outer</sub> (min) must exceed these values.

Note 3: Transmitter reflectance is defined looking into the transmitter.

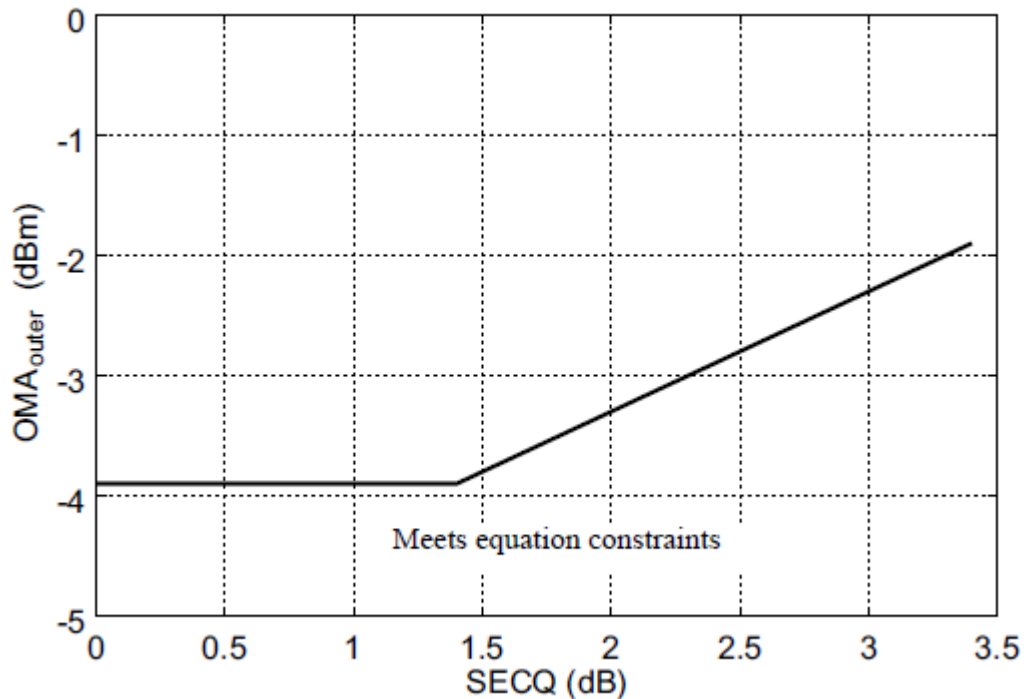
Note 4: Average receive power, each lane (min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance.

Note 5: For when Pre-FEC BER is  $2.4 \times 10^{-4}$ .

Note 6: Receiver sensitivity (OMA<sub>outer</sub>), each lane (max) is informative and is defined for a transmitter with a value of SECQ up to 3.4 dB.

Note 7: Measured with conformance test signal at TP3 (see 124.8.9) for the BER specified in 124.1.1.

Note 8: These test conditions are for measuring stressed receiver sensitivity. They are not characteristics of the receiver.



**Figure 3 Receiver Sensitivity**

**Table 5 RX\_LOS Characteristics**

No.	Parameter	Symbol	Min.	Typ.	Max.	Unit	Remarks
1	Receiver Loss of Signal Indicator Assert Level	RX_LOS	-15	-	-7.9	dBm	Average power
2	Receiver Loss of Signal Indicator De-assert Level	RX_LOS	-	-	-7.4	dBm	Average power
3	Hysteresis		0.5			dB	



### **3 HIGH SPEED DATA INTERFACE**

#### **3.1 Rx(n)(p/n)**

Rx(n)(p/n) are QSFP-DD module receiver data outputs. Rx(n)(p/n) are AC-coupled 100 Ohm differential lines that should be terminated with 100 Ohm differentially at the Host ASIC. The QSFP-DD module host interface is internally AC coupled, so AC-coupling is not required on the host PCB.

Output squelch for loss of optical input signal (RX Squelch) is required and shall function as follows. In the event of the Rx input signal on any optical port becoming equal to or less than the level required to assert LOS, the receiver output(s) associated with that Rx port shall be squelched. A single Rx optical port can be associated with more than one Rx output. In the squelched state, output impedance levels are maintained, while the differential voltage amplitude shall be less than 50 mVpp.

#### **3.2 Tx(n)(p/n)**

Tx(n)(p/n) are QSFP-DD module transmitter data inputs. They are AC-coupled 100 Ohm differential lines with 100 Ohm differential terminations inside the QSFP-DD optical module. The AC coupling is implemented inside the QSFP-DD optical module and not required on the Host board.

Output squelch for loss of electrical signal (Tx Squelch) is an optional function. Where implemented, it shall function as follows. In the event of the differential, peak-to-peak electrical signal amplitude on any electrical input channel becoming less than 70 mVpp, then the transmitter optical output associated with that electrical input channel shall be squelched and the associated TxLOS flag set. If multiple electrical input channels are associated with the same optical output channel, the loss of any of the incoming electrical input channels causes the optical output channel to be squelched.

For applications, e.g. Ethernet, where the transmitter off condition is defined in terms of average power, squelching by disabling the transmitter is recommended and for applications, e.g. InfiniBand, where the transmitter off condition is defined in terms of OMA, squelching the transmitter by setting the OMA to a low level is recommended.

## 4 CONTROL INTERFACE

### 4.1 Low Speed Control Pins

In addition to the 2-wire serial interface the transceiver has the following low speed signals for control and status: ModSelL, ResetL, InitMode, ModPrsL and IntL. See the QSFP-DD MSA Hardware Specification for detailed descriptions of each signal.

### 4.2 Low Speed Electrical Specifications

Low speed signaling other than SCL and SDA is based on Low Voltage TTL (LVTTTL) operating at Vcc.

**Table 6 Low Speed Control and Sense Signals**

Parameter	Symbol	Min	Max	Unit	Condition
SCL and SDA	VOL	0	0.4	V	IOL(max)=3mA for fast mode, 20mA for fast-mode plus
	VOH	Vcc-0.5	Vcc+0.3	V	
SCL and SDA	VIL	-0.3	Vcc*0.3	V	
	VIH	VCC*0.7	Vcc+0.5	V	
Capacitance for SCL and SDA I/O signal	Ci		14	pF	
Total bus capacitive load for SCL and SDA	Cb		100	pF	For 400kHz clock rate use MAX 3.0k ohm pull-up resistor. For 1000kHz clock rate refer to Figure 40 in Reference [3].
	Cb		200	pF	For 400kHz clock rate use MAX 1.6k ohm pullup resistor. For 1000kHz clock rate refer to Figure 40 in Reference [3].
InitMode, ResetL and ModSelL	VIL	-0.3	0.8	V	
	VIH	2	VCC+0.3	V	
	Iin		360	uA	0V<Vin<Vcc
IntL	VOL	0	0.4	V	IOL=2.0mA
	VOH	VCC-0.5	VCC+0.3	V	10k ohms pull up to Host Vcc
ModPrsL	VOL	0	0.4	V	IOL=2.0mA
	VOH				ModPrsL can be implemented as a short-circuit to GND on the module

## 2-Wire Management Interface

The QSFP-DD Module supports alarm, control and monitor functions via a two-wire interface bus. Upon module initialization, these functions are available. QSFP-DD two-wire electrical interface consists of 2 pins of SCL (2-wire serial interface clock) and SDA (2-wire serial interface data). The low speed signaling is based on Low Voltage CMOS (LVCMOS) operating at Vcc. Hosts shall use a pull-up resistor connected to Vcc\_host on the 2-wire interface SCL (clock) and SDA (Data) signals. The timing requirements on the two-wire interface are listed in Table 7 and Figure 4.

**Table 7 Management Interface Timing**

Parameter	Symbol	Fast Mode Plus (1 MHz)		Unit	Conditions
		Min	Max		
Clock Frequency	fSCL	0	1000	kHz	
Clock Pulse Width Low	tLOW	0.50		µs	
Clock Pulse Width High	tHIGH	0.26		µs	
Time bus free before new transmission can start	tBUF	1		µs	Between STOP and START and between ACK and ReStart
START Hold Time	tHD.STA	0.26		µs	The delay required between SDA becoming low and SCL starting to go low in a START
START Setup Time	tSU.STA	0.26		µs	The delay required between SCL becoming high and SDA starting to go low in a START
Data In Hold Time	tHD.DAT	0		µs	
Data In Setup Time	tSU.DAT	0.1		µs	
Input Rise Time	tR		120	ns	From (VIL,MAX=0.3*Vcc) to (VIH,MIN=0.7*Vcc)
Input Fall Time	tF		120	ns	From (VIH,MIN=0.7*Vcc) to (VIL,MAX=0.3*Vcc)
STOP Setup Time	tSU.STO	0.26		µs	
STOP Hold Time	tHD.STO	0.26		us	
Aborted sequence bus release	Deselect _Abort		2	ms	Delay from a host de-asserting ModSelL (at any point in a bus sequence) to the QSFP-DD module releasing SCL and SDA
ModSelL Setup Time <sup>1</sup>	tSU.Mod SelL	2		ms	ModSelL Setup Time is the setup time on the select lines before the start of a host initiated serial bus

Parameter	Symbol	Fast Mode Plus (1 MHz)		Unit	Conditions
		Min	Max		
		ModSelL Hold Time <sup>1</sup>	tHD.Mod SelL		
Serial Interface Clock Holdoff "Clock Stretching"	T_clock_hold		500	us	Maximum time the QSFP-DD module may hold the SCL line low before continuing with a read or write operation
Complete Single or Sequential Write to non-volatile registers	tWR		80	ms	Complete Write of up to 8 Bytes
Accept a single or sequential write to volatile memory.	tNACK		80	ms	Time required for the module to accept a single or sequential write to volatile memory.
Endurance (Write Cycles)		50k			Module Case Temperature= 70°C

Note 1: When the host has determined that module is QSFP-DD, the management registers can be read to determine alternate supported ModSelL set up and hold times.

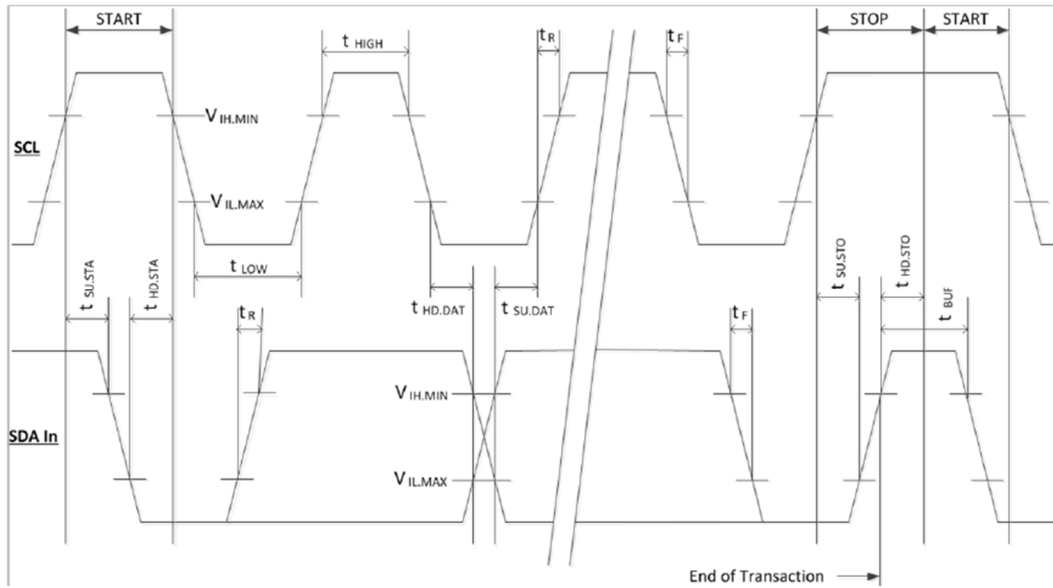


Figure 4 2-Wire Interface Timing Diagram

### 4.3 Soft Control and Status Functions

Table 8 lists the required timing performance for software controlled control and status functions.

**Table 8 Control and Status Timing Requirements**

Parameter	Symbol	Min	Max	Unit	Conditions
MgmtInitDuration	Max MgmtInit Duration		2000	ms	Time from power on <sup>1</sup> , hot plug or rising edge of reset until completion of the MgmtInit State
ResetL Assert Time	t_reset_init	10		µs	Minimum pulse time on the ResetL signal to initiate a module reset.
IntL Assert Time	ton_IntL		200	ms	Time from occurrence of condition triggering IntL until Vout:IntL=Vol
IntL Deassert Time	toff_IntL		500	µs	Time from clear on read <sup>2</sup> operation of associated flag until Vout:IntL=Voh. This includes deassert times for Rx LOS, Tx Fault and other flag bits.
Rx LOS Assert Time	ton_los		100	ms	Time from Rx LOS condition present to Rx LOS bit set (value = 1b) and IntL asserted.
Rx LOS Assert Time (optional fast mode)	ton_losf		100	ms	Time from Rx LOS state to Rx LOS bit set (value = 1b) and IntL asserted.
Rx LOS Deassert Time (optional fast mode)	toff_losf		100	ms	Time from Rx LOS condition absent to negation of Rx LOS status bit.
Tx Fault Assert Time	ton_Txfault		200	ms	Time from Tx Fault state to Tx Fault bit set (value=1b) and IntL asserted.
Flag Assert Time	ton_flag		200	ms	Time from occurrence of condition triggering flag to associated flag bit set (value=1b) and IntL asserted.
Mask Assert Time	ton_mask		100	ms	Time from mask bit set (value=1b) <sup>3</sup> until associated IntLassertion is inhibited
Mask Deassert Time	toff_mask		100	ms	Time from mask bit cleared (value=0b) <sup>3</sup> until associated IntL operation resumes

Note 1: Power on is defined as the instant when supply voltages reach and remain at or above the minimum level specified in Table 7.





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**QSFP-DD form factor with Diagnostic Monitoring**  
**40GBASE QSFP-DD DR4**

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Note 2: Measured from the rising edge of SDA in the stop bit of the read transaction.

Note 3: Measured from the rising edge of SDA in the stop bit of the write transaction.

Note 4: Rx LOS condition is defined at the optical input by the relevant standard.

#### 4.4 Squelch and TxRx Disable Assert, De-assert and Enable/Disable Timing

Table 9 lists the required timing performance for assert, de-assert, enable and disable of the Tx Squelch, Rx Squelch, Tx Disable and Rx Output Disable functions.

**Table 9 Squelch & TxRx Disable Timing**

Parameter	Symbol	Max	Unit	Conditions
Rx Squelch Assert Time	ton_Rxsq	15	ms	Time from loss of Rx input signal until the squelched output condition is reached.
Rx Squelch De-assert Time	toff_Rxsq	(5000)	ms	Time from resumption of Rx input signals until normal Rx output condition is reached.
Tx Squelch Assert Time	ton_Txsq	400	ms	Time from loss of Tx input signal until the squelched output condition is reached.
Tx Squelch De-assert Time	toff_Txsq	(5000)	ms	Time from resumption of Tx input signals until normal Tx output condition is reached.
Tx Disable Assert Time	ton_txdis	100	ms	Time from the stop condition of the Tx Disable write sequence <sup>1</sup> until optical output falls below 10% of nominal
Tx Disable Assert Time (optional fast mode)	ton_txdisf	3	ms	Time from Tx Disable bit set (value = 1b) <sup>1</sup> until optical output falls below 10% of nominal
Tx Disable De-assert Time	toff_txdis	400	ms	Time from Tx Disable bit cleared (value = 0b) <sup>1</sup> until optical output rises above 90% of nominal
Tx Disable De-assert Time (optional fast mode)	toff_txdisf	10	ms	Time from Tx Disable bit cleared (value = 0b) <sup>1</sup> until optical output rises above 90% of nominal
Rx Output Disable Assert Time	ton_rxdis	100	ms	Time from Rx Output Disable bit set (value = 1b) <sup>1</sup> until Rx output falls below 10% of nominal
Rx Output Disable De-assert Time	toff_rxdis	100	ms	Time from Rx Output Disable bit cleared (value = 0b) <sup>1</sup> until Rx output rises above 90% of nominal
Squelch Disable Assert Time	ton_sqdis	Not applicable (Tx/Rx Auto Squelch Disable not supported)		This applies to Rx and Tx Squelch and is the time from bit set (value = 0b) <sup>1</sup> until squelch functionality is disabled.
Squelch Disable	toff_sqdis	Not applicable (Tx/Rx		This applies to Rx and Tx Squelch and



**1310nm Single-mode Transceiver**  
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De-assert Time		Auto Squelch Disable not supported)	isthe time from bit cleared (value = 0b) <sup>1</sup> until squelch functionality is enabled
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Note 1: Measured from LOW to HIGH SDA signal transition of the STOP condition of the write transaction.

## 5 POWER

The power supply has six designated pins, VccTx, VccTx1, Vcc1, Vcc2, VccRx, VccRx1 in the connector. Vcc1 and Vcc2 are used to supplement VccTx, VccTx1, VccRx or VccRx1 at the discretion of the module vendor. Power is applied concurrently to these pins.

A host board together with the QSFP-DD module(s) forms an integrated power system. The host supplies stable power to the module. The module limits electrical noise coupled back into the host system and limits inrush charge/current during hot plug insertion.

All power supply requirements in Table 6 shall be met at the maximum power supply current. No power sequencing of the power supply is required of the host system since the module sequences the contacts in the order of ground, supply and signals during insertion.

QSFP56-DD modules are categorized into several power classes as listed in Table 10. The power class of TRD5H01 is class 6.

**Table 10 Maximum Power Classes**

Power Class	Max Power (W)
1	1.5
2	3.5
3	7.0
4	8.0
5	10
6	12
7	14
8	>14

## 5.1 Host Board Power Supply Filtering

The host board should use the power supply filtering equivalent to that shown in Figure 5.

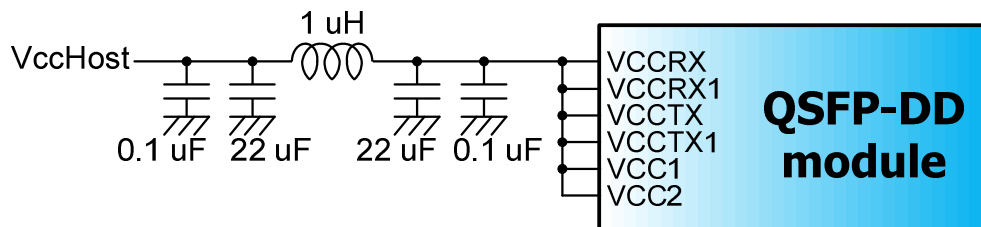


Figure 5 Recommended Host Board Power Supply Filtering

## 5.2 Module Power Supply Specification

In order to avoid exceeding the host system power capacity, upon hot-plug, power cycle or reset, all QSFP-DD modules shall power up in Low Power Mode if InitMode is asserted. If InitMode is not asserted, the module will proceed to High Power Mode without host intervention. Figure 3 shows waveforms for maximum instantaneous, sustained and steady state currents for Low Power and High Power modes. Specification values for maximum instantaneous, sustained and steady state currents at each power class are given in Table 2.

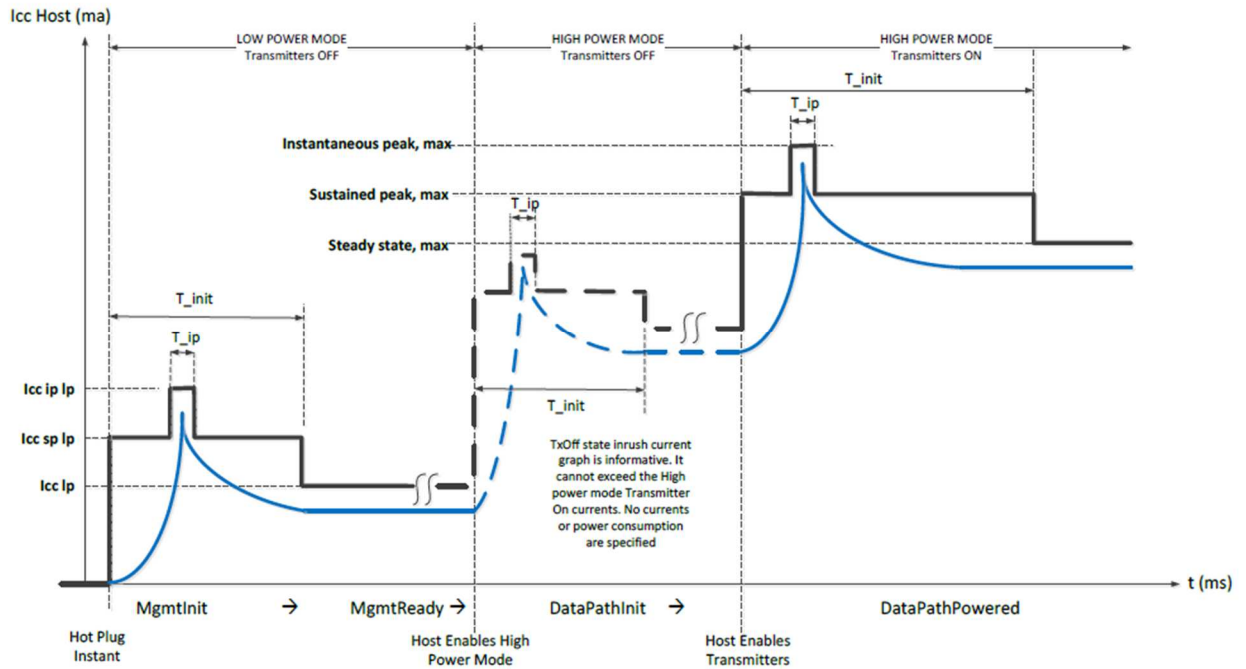


Figure 6 Instantaneous and Sustained Peak Currents for Icc Host

6 PIN ASSIGNMENT

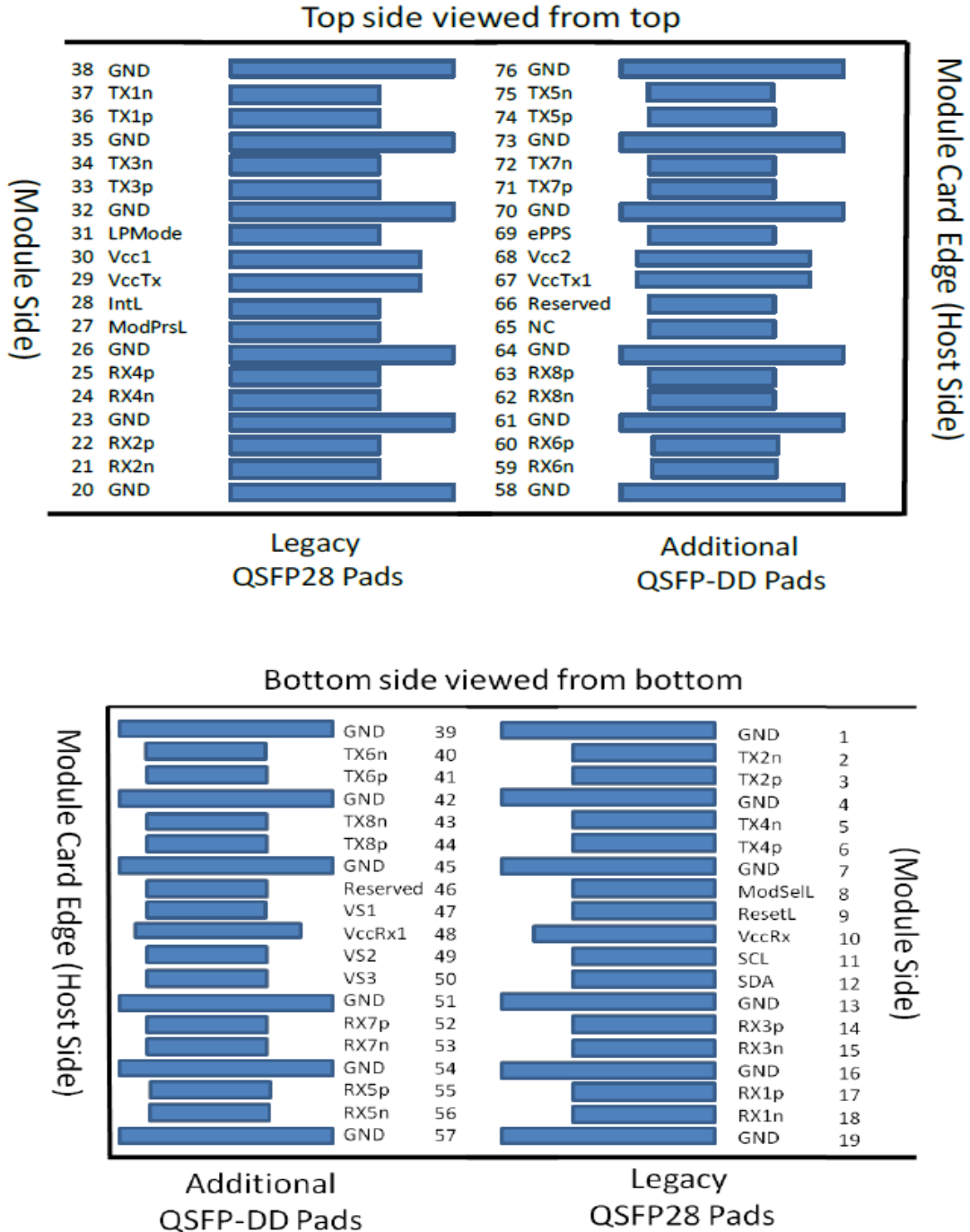


Figure 7 Pin Configuration



**1310nm Single-mode Transceiver**  
**QSFP-DD form factor with Diagnostic Monitoring**  
**400GBASE QSFP-DD DR4**

**Table 11 Pin Description**

Pad	Logic	Symbol	Description	Plug Sequence <sup>4</sup>	Notes
1		GND	Ground	1B	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3B	
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	3B	
4		GND	Ground	1B	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3B	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	3B	
7		GND	Ground	1B	1
8	LVTTTL-I	ModSelL	Module Select	3B	
9	LVTTTL-I	ResetL	Module Reset	3B	
10		VccRx	+3.3V Power Supply Receiver	2B	2
11	LVC MOS-I/O	SCL	2-wire serial interface clock	3B	
12	LVC MOS-I/O	SDA	2-wire serial interface data	3B	
13		GND	Ground	1B	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	3B	
15	CML-O	Rx3n	Receiver Inverted Data Output	3B	
16		GND	Ground	1B	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3B	
18	CML-O	Rx1n	Receiver Inverted Data Output	3B	
19		GND	Ground	1B	1
20		GND	Ground	1B	1
21	CML-O	Rx2n	Receiver Inverted Data Output	3B	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	3B	
23		GND	Ground	1B	1
24	CML-O	Rx4n	Receiver Inverted Data Output	3B	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	3B	
26		GND	Ground	1B	1
27	LVTTTL-O	ModPrsL	Module Present	3B	
28	LVTTTL-O	IntL	Interrupt	3B	
29		VccTx	+3.3V Power supply transmitter	2B	2
30		Vcc1	+3.3V Power supply	2B	2
31	LVTTTL-I	LPMODE	Low Power mode;	3B	
32		GND	Ground	1B	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	3B	
34	CML-I	Tx3n	Transmitter Inverted Data Input	3B	
35		GND	Ground	1B	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3B	
37	CML-I	Tx1n	Transmitter Inverted Data Input	3B	
38		GND	Ground	1B	1



**1310nm Single-mode Transceiver**  
**QSFP-DD form factor with Diagnostic Monitoring**  
**400GBASE QSFP-DD DR4**

Pad	Logic	Symbol	Description	Plug Sequence <sup>4</sup>	Notes
39		GND	Ground	1A	1
40	CML-I	Tx6n	Transmitter Inverted Data Input	3A	
41	CML-I	Tx6p	Transmitter Non-Inverted Data Input	3A	
42		GND	Ground	1A	1
43	CML-I	Tx8n	Transmitter Inverted Data Input	3A	
44	CML-I	Tx8p	Transmitter Non-Inverted Data Input	3A	
45		GND	Ground	1A	1
46		Reserved	For future use	3A	3
47		VS1	Module Vendor Specific 1	3A	3
48		VccRx1	3.3V Power Supply	2A	2
49		VS2	Module Vendor Specific 2	3A	3
50		VS3	Module Vendor Specific 3	3A	3
51		GND	Ground	1A	1
52	CML-O	Rx7p	Receiver Non-Inverted Data Output	3A	
53	CML-O	Rx7n	Receiver Inverted Data Output	3A	
54		GND	Ground	1A	1
55	CML-O	Rx5p	Receiver Non-Inverted Data Output	3A	
56	CML-O	Rx5n	Receiver Inverted Data Output	3A	
57		GND	Ground	1A	1
58		GND	Ground	1A	1
59	CML-O	Rx6n	Receiver Inverted Data Output	3A	
60	CML-O	Rx6p	Receiver Non-Inverted Data Output	3A	
61		GND	Ground	1A	1
62	CML-O	Rx8n	Receiver Inverted Data Output	3A	
63	CML-O	Rx8p	Receiver Non-Inverted Data Output	3A	
64		GND	Ground	1A	1
65		NC	No Connect	3A	3
66		Reserved	For future use	3A	3
67		VccTx1	3.3V Power Supply	2A	2
68		Vcc2	3.3V Power Supply	2A	2
69	LVTTL-I	Reserved	<del>Precision Time Protocol (PTP) reference clock input</del>	3A	3
70		GND	Ground	1A	1
71	CML-I	Tx7p	Transmitter Non-Inverted Data Input	3A	
72	CML-I	Tx7n	Transmitter Inverted Data Input	3A	
73		GND	Ground	1A	1
74	CML-I	Tx5p	Transmitter Non-Inverted Data Input	3A	
75	CML-I	Tx5n	Transmitter Inverted Data Input	3A	
76		GND	Ground	1A	1

Note 1: QSFP-DD uses common ground (GND) for all signals and supply (power). All are common within the QSFP-DD module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.

Note 2: VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 shall be applied concurrently. Requirements defined for the host side of the Host Card Edge Connector are listed in Table 7. VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 may be internally connected within the module in any combination. The connector Vcc pins are each rated for a maximum current of 1000 mA.

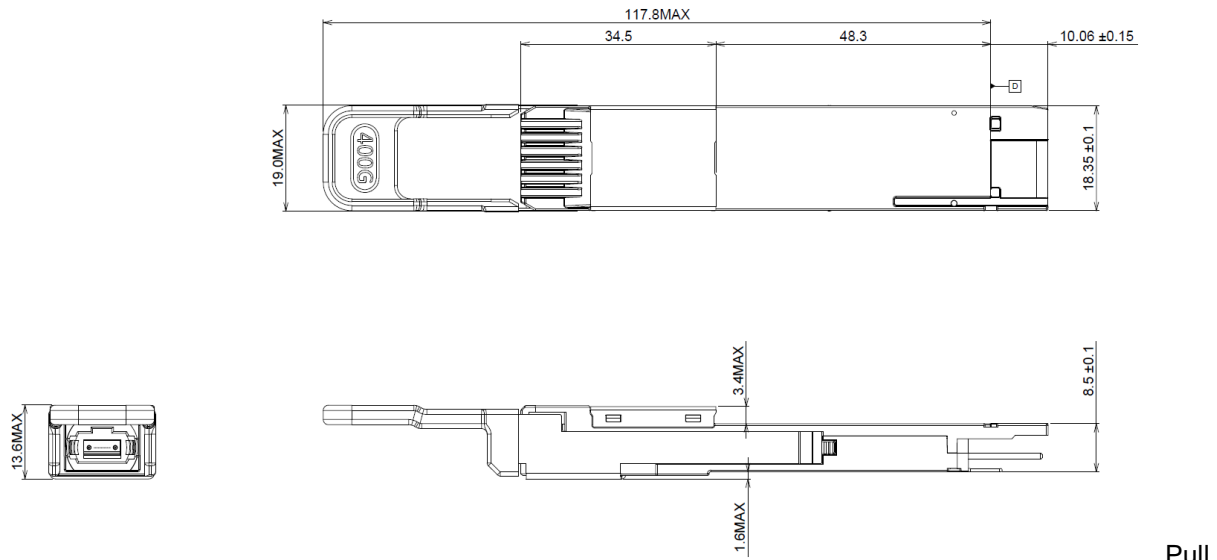
Note 3: All Vendor Specific, Reserved, No Connect and ePPS (if not used) pins may be terminated with 50 Ohms to ground on the host. Pad 65 (No Connect) shall be left unconnected within the module. Vendor specific and Reserved pads shall have an impedance to GND that is greater than 10 kOhms and less than 100 pF.

Note 4: Plug Sequence specifies the mating sequence of the host connector and module. The sequence is 1A, 2A, 3A, 1B, 2B, 3B. (see Figure 2 for pad locations) Contact sequence A will make, then break contact with additional QSFP-DD pads. Sequence 1A, 1B will then occur simultaneously, followed by 2A, 2B, followed by 3A, 3B.



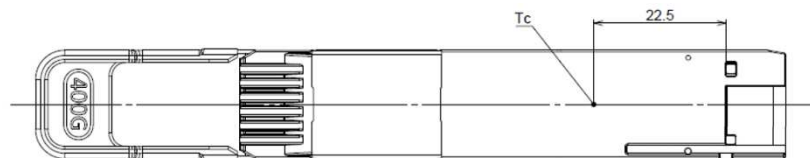
## 7 MECHANICAL DIMENSIONS

Unit: mm

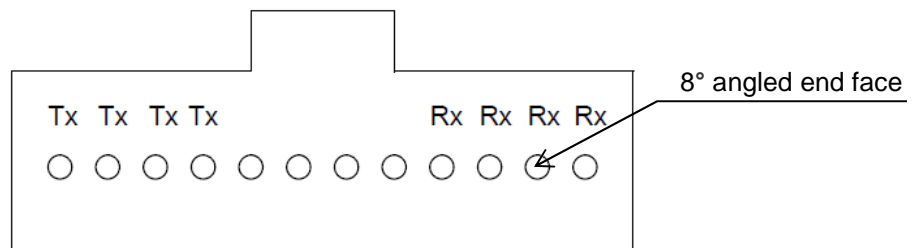


tab color: Yellow

**Figure 8 Mechanical Dimensions**



**Figure 9 Case temperature measurement point**



Looking into the connector, transmitter is on the left.

**Figure 10 Optical Interface**

## 8 COMPONENT LABEL DESIGN

13 mm x 25 mm

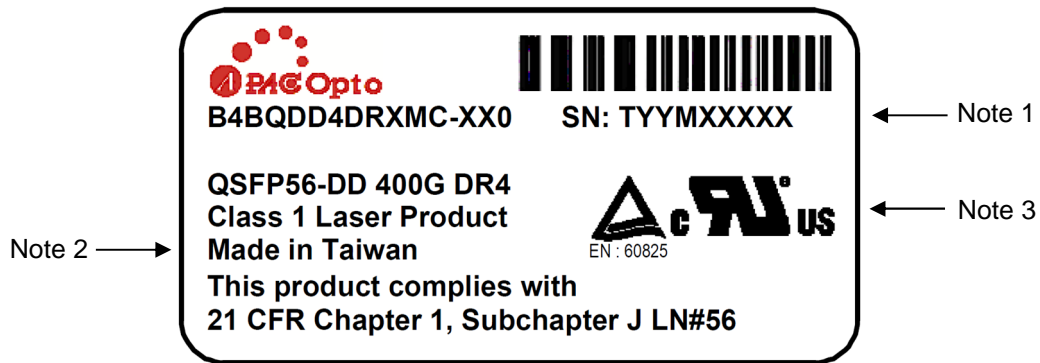


Figure 11 Component Label

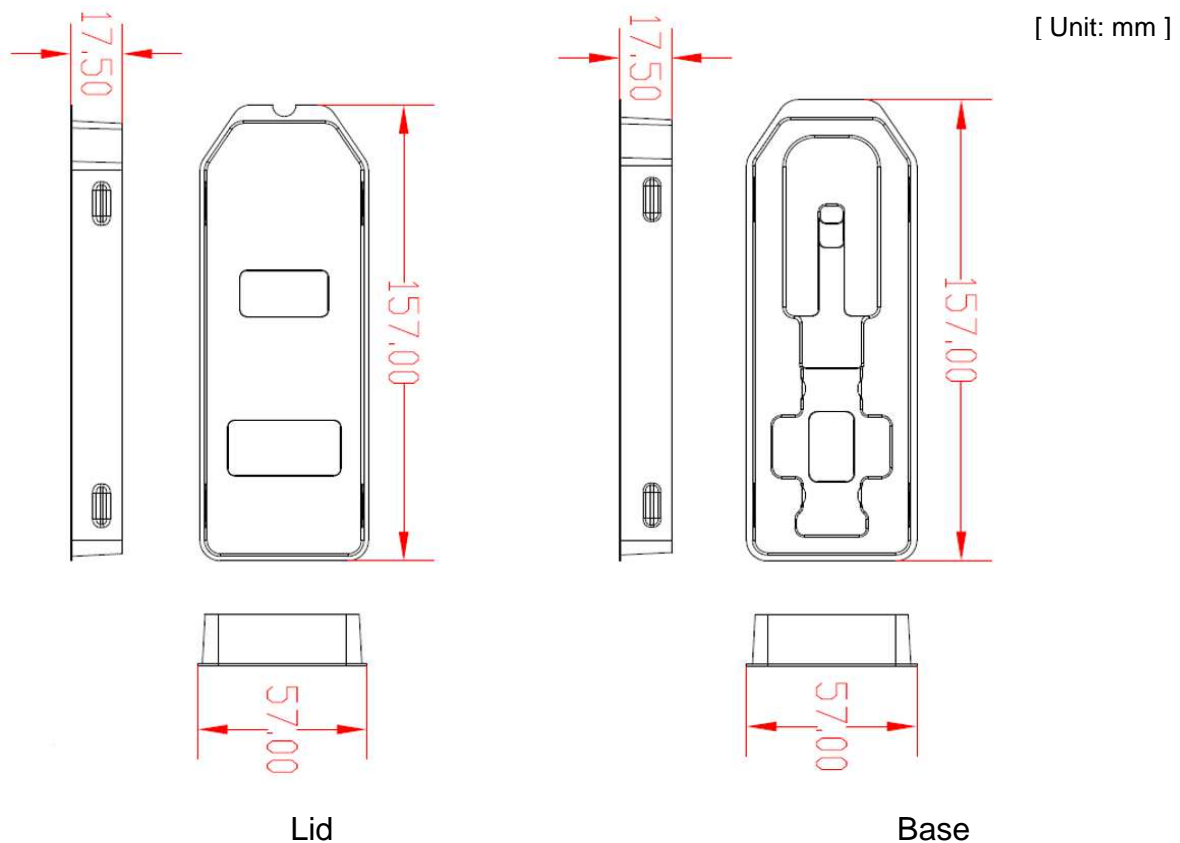
Table 12 Label Description

Note 1	Serial Number	TYYMXXXXX (ex. T23A01234) Manufacturing location. T = Taiwan YY: year of manufactured (ex. 23 = 2023) M: Month of manufactured (A for Jan., B for Feb., C for Mar., D for Apr., E for May, F for June, G for July, H for Aug., J for Sep., K for Oct., L for Nov., M for Dec.) XXXXX: Base 32 number (5 digits sequential number from 00001 to ZZZZZ, omit "I", "O", "V", "W")
Note 2	Manufacture Location	Made in Taiwan
Note 3	Certification	Certificate logos may not be printed on labels of Alpha and Beta samples

## 9 PACKAGING.

### Individual Tray for QSFP-DD Transceiver

- Size: 157 x 57 x 17.5 mm typ
- Material: PET (Polyethylene Terephthalate)
- Color: Clear
- Tray label: Non-tray label to consider recycle.



**Figure 12 Individual Tray Dimensions**

Note: Finally, place the individual tray into the following packing sleeve.





## 10 REGULATORY COMPLIANCE

Certification	Standard
EMC/EMI	FCC Part 15, Subpart B (Class B) EN55032 (Class B)
ESD	EN61000-4-2, criterion B JEDEC JESD22-A114-B Human Body Model
Laser Safety	Class 1 laser product per IEC 60825-1:2014 3rd edition and is considered non-hazardous when operated within the limits of this specification. This device complies with 21 CFR 1040.10 except for deviations pursuant to Laser Notice No. 56.
Environmental	RoHS 10 (2011/65/EU + 2015/863) ISA S71.04 G2

CAUTION: Use of controls or adjustments or performance of procedures other than those specified herein may result in hazardous radiation exposure.

## 11 REFERENCES

- IEEE “802.3-2018 Section 8”
- QSFPDD MSA - “QSFP-DD Hardware Specification for QSFP DOUBLE DENSITY 8X PLUGGABLE TRANSCEIVE Rev. 5.0”
- QSFP-DD Management Interface Specification Rev 4.0
- SNIA - “SFF-8636 Rev 2.5”

## 12 ORDERING INFORMATION

Table 13 Product Code

	B	4B	QDD	4	DRX	M	C	-	X <sub>13</sub> X <sub>14</sub>	0
	1	2	3	4	5	6	7		8	9
Item	Parameter		Symbol							
1	Product Category		B							
2	Data rate		4B: 400G							
3	Module Form Factor		QDD: QSFP-DD							
4	Channel (TX)		4: 4CH							
5	Distance		DRX: DR							
6	Connector Type		M: MPO12							
7	Operating Temperature Range		C: 0~70C							
8	Customer Code		XX: Standard Product							
9	Revision		0							



**1310nm Single-mode Transceiver  
QSFP-DD form factor with Diagnostic Monitoring  
400GBASE QSFP-DD DR4**

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### 13 REVISION HISTORY

Rev.	Date	Note
1.0	2023/06/20	New released

For sales and support in your region, please go to [sales@apacoe.com.tw](mailto:sales@apacoe.com.tw)